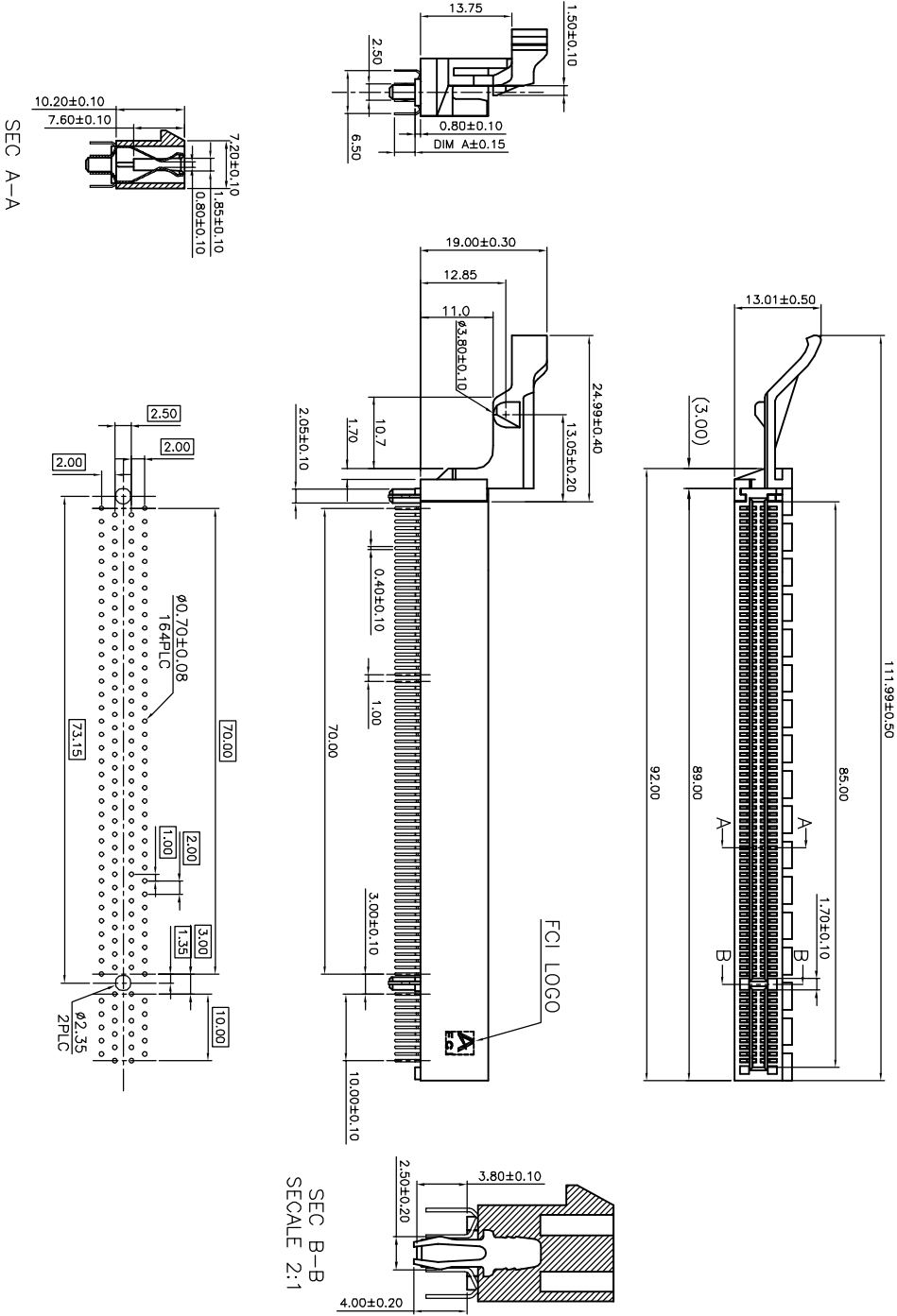




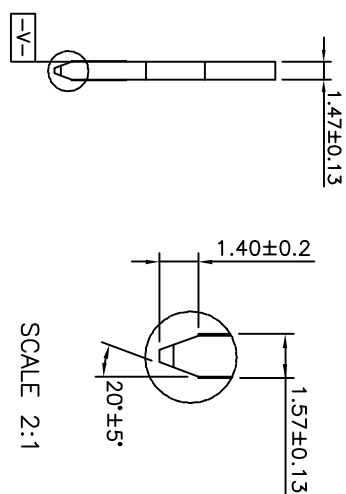
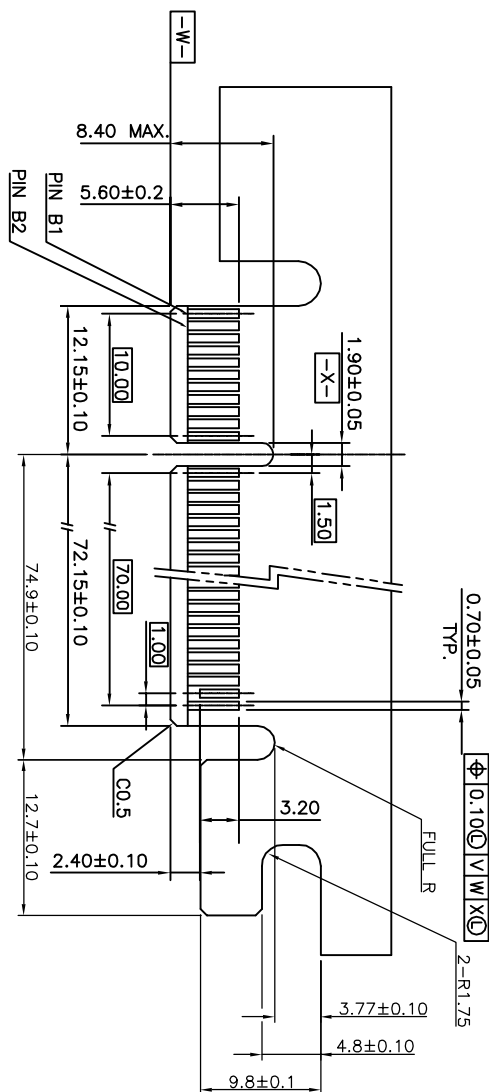
SEC B-B
SECALE 2:1

SEC A-A

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		FCI	
itr	ecn no	dr	date	linear	projection	title	www.fciconnect.com
A	T05-0046	J.H	2/23/05	.XX ± 0.38	MM	PCI-E INTEGRATED TYPE	
B	T05-0067	J.H	3/28/05	.XXX ± 0.10	MM	CARD EDGE ASS'Y	
C	T05-0227	J.H	09/30/05	0° ± 2°	MM	product family	EDGE CARD
D	T06-0187	J.H	11/13/06	dr	MM	size dwg no	10046742
E	T07-1125	J.H	08/02/07	engr	MM	code	TWN
				chr	STERLING LIN	2/23/05	
				appr	HC UOU	2/23/05	
sheet	revision	E	E	E	1:1	A4	10046742
index	sheet	1	2	3			

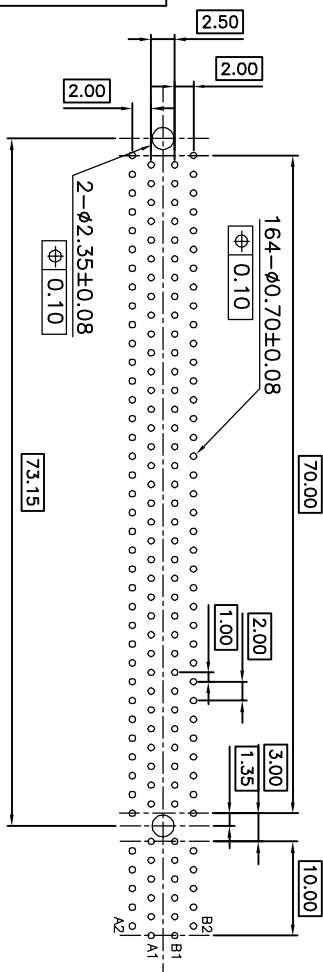
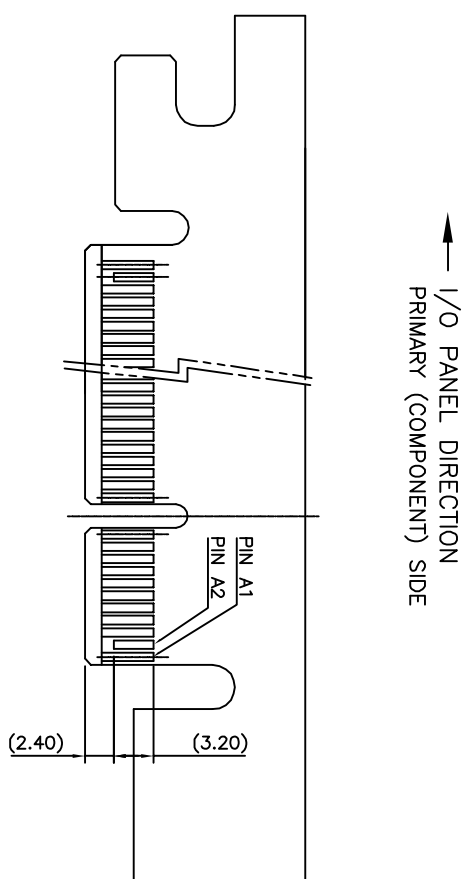
ACAD

cage code
22526



SCALE 2:1

ADD-IN CARD EDGE-FINGER DIMENSIONS



RECOMMENDED FOOTPRINT LAYOUT

I/O PANEL DIRECTION →
SECONDARY (SOLDER) SIDE

mat'l. code			tolerances unless otherwise specified			CUSTOMER COPY		 www.fciconnect.com	
itr	ecn no	dr	dtle	linear		 projection	title	PCI-E INTEGRATED TYPE CARD EDGE ASS'Y	code
E				.XX ± 0.25					
				.XXX ± 0.10					
				angles		 MM	product family	EDGE CARD	sheet
				0° ± 2°					
				dr JASON HSU 2/23/05					
				engr JASON HSU 2/23/05		scale	A4	10046742	2 of
				chr STERLING LIN 2/23/05					
				opnd HC LIU 2/23/05					
sheet index	revision sheet								

1-2

3

4

NOTES: 1. MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0,
COLOR IN BLACK.
LATCHES: THERMOPLASTIC WITH GLASS FIBER, UL94 HB,
COLOR IN BLACK.
CONTACTS: COPPER ALLOY.
BOARDLOCKS: COPPER ALLOY.

2. FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA.
100u"MIN. TIN/LEAD OR 60u" MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS.
50u"MIN. NICKEL UNDERPLATING OVER ALL.

BOARDLOCKS : 100u" TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS.
50u"MIN. NICKEL UNDERPLATING OVER ALL.

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER BY 20 DEGREE.

4. DURABILITY: 50 CYCLES.

5. ROHS COMPATIBLE PRODUCT SPECIFICATIONS
a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 2.5um min. MATTE PURE TIN OVER 1.27um MIN.

b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C±5C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

[illegible]

HOUSING COLOR OPTIONS

1-BLACK FOR BASE & RM
2-BLACK FOR BASE & WHITE FOR RM
3-BLUE (287U) FOR BASE & RM
4-BLUE (297U) FOR BASE & RM

PEGS OPTIONS

1-METAL & PLASTIC COMPOUND

TERMINAL PLATING OPTIONS

	TAIL LENGTH OPTION (DIM A)
0-50u" Ni UNDERPLATE	1-3.10MM
30u" Au CONTACT AREA	2-2.30MM
100u" TIN TAIL AREA	
4-60u" Ni UNDERPLATE	

PACKAGING OPTIONS

T-TRAY PACK

POS OPTIONS

3-164

TAIL LENGTH OPTION (DIM A)

1- 3.10MM
2- 2.30MM

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com	
ltr	ecn no	dr	date	projection		title	
E				linear		PCI-E INTEGRATED TYPE	
				.XX ± 0.25		CARD EDGE ASS'Y	
				.XXX ± 0.10			
				angles			
				0° ± 2°			
				dr		product family	
				JASON HSU 2/23/05		EDGE CARD	
				engr JASON HSU 2/23/05		code	
				chr STERLING LIN 2/23/05		TWN	
				apprd		sheet	
				HC LIU 2/23/05		3 of	
sheet	revision			scale			
index	sheet			1:1			